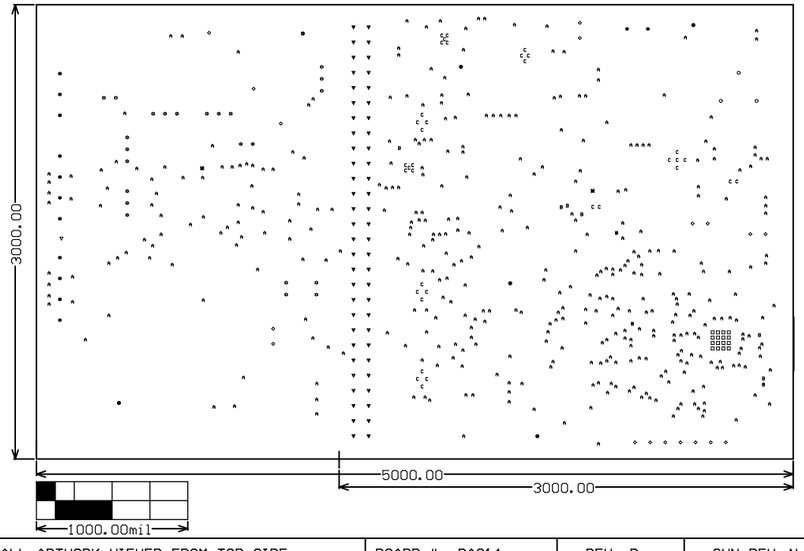
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric1		9.00mil	4.2	
2	Ground		1.40mil		
	Dielectric 3	FR-4	39.00mil	4.2	
3	Power		1.40mil		
	Dielectric 2		9.00mil	4.2	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
▽	1	28.00mil (0.711mm)	PTH	Round
⊠	2	16.00mil (0.406mm)	PTH	Round
○	3	43.31mil (1.100mm)	PTH	Round
⊕	6	80.71mil (2.050mm)	PTH	Round
B	9	13.00mil (0.330mm)	PTH	Round
✱	13	50.00mil (1.270mm)	PTH	Round
□	16	8.00mil (0.203mm)	PTH	Round
◇	18	40.00mil (1.016mm)	PTH	Round
☼	23	35.00mil (0.889mm)	PTH	Round
C	35	7.87mil (0.200mm)	PTH	Round
▽	56	40.16mil (1.020mm)	PTH	Round
A	393	10.00mil (0.254mm)	PTH	Round
	575 Total			



DESIGN INFORMATION

MIN. TRACK WIDTH: 6 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 20 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

TEXAS INSTRUMENTS

PROJECT TITLE: ADS1x4S08EVM
DESIGNED FOR: Public Release
FILE NAME: PA014B.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PA014	REV: B	SVN REV: Not in version control
LAYER NAME = [illegible]ions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 7/14/2025 4:58:16 PM		TEXAS INSTRUMENTS

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ENGINEER:	LAYOUT BY:
Robert Benjamin	Hupp/Benjamin
SCALE: 1.00	ALTIUM DESIGNER VERSION: 24.1.2.44